N-Channel 100V, 2.3mΩ Typ. Power MOSFET

Description

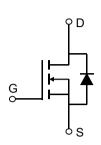
Features

• 100V, 165A

$$R_{DS(ON)}$$
 Typ = 2.3m Ω @ V_{GS} = 10 V

$$R_{DS(ON)}$$
 Typ = $3m\Omega$ @ V_{GS} = 4.5V

- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGL1002A	CRMGGL1002A	PDFN5x6-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage	±20	V	
_	Continuous Drain Current	T _C = 25°C	165	А
I _D		T _C = 100°C	99	А
I _{DM}	Pulsed Drain Current ⁽¹⁾		660	А
E _{AS}	Single Pulsed Avalanche Energy (2)		484	mJ
P_D	Power Dissipation	T _C = 25°C	167	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		0.75	°C/W
T_{J}, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

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CRMGGL1002A

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni
Off Chara	acteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				<u>C</u>	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.5	2	V
Б		$V_{GS} = 10V, I_D = 30A$	-	2.3	3	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 4.5V, I_D = 25A$	-	3	3.9	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-(4962	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 50V,$ f = 100KHz	X-\	1509	-	pF
C_{rss}	Reverse Transfer Capacitance	I = TOOKIZ		39	-	pF
Q_g	Total Gate Charge		J -	35	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_{D} = 30A$	-	12.5	-	nC
Q_gd	Gate Drain("Miller") Charge	VDS = 00 V, 1D = 00 V	-	11	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime	.()	-	10	-	ns
t_r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	9	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = 30A, R_{GEN} = 3Ω	-	38	-	ns
t_f	Turn-Off Fall Time		-	15	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
I _S	Maximum Continuous Drain to Source Diode Forward Current			-	165	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	660	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 - 204 di/dt - 4004/:	-	39	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 30A$, di/dt = 100A/us	-	48	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =44A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

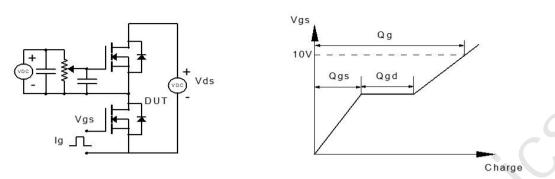


Figure 1: Gate Charge Test Circuit & Waveform

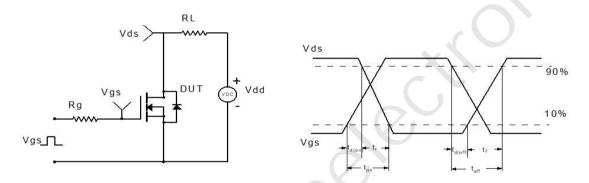


Figure 2: Resistive Switching Test Circuit & Waveform

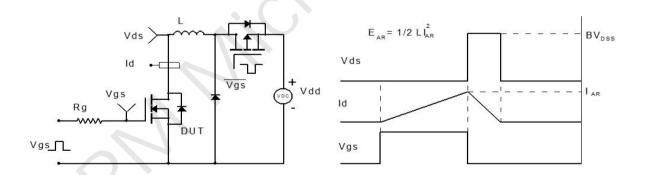


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

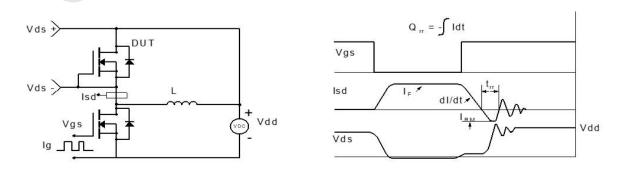
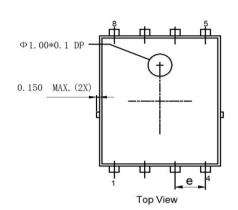


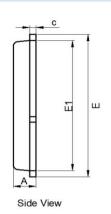
Figure 4: Diode Recovery Test Circuit & Waveform

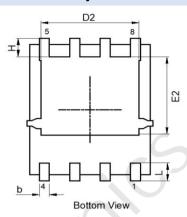
CRMGGL1002A

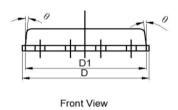
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Package Mechanical Data(PDFN5x6-8L)









DIM.	MILLIMETER			
DIN.	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
b	0.31	0.41	0.51	
С	0.21	0.25	0.34	
D	5.05	5.20	5.40	
D1	4.95	5.05	5.15	
D2	4.00	4.10	4.20	
E	6.30	6.40	6.50	
E1	5.75	5.85	5.95	
E2	3.43	3.53	3.63	
е	1.27BSC			
Н	0.73	0.83	0.93	
L	0.61	0.71	0.81	
θ	0°		12°	

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